EUROPEAN PATENT OFFICE U.S. PATENT AND TRADEMARK OFFICE

CPC NOTICE OF CHANGES 1821

DATE: JANUARY 1, 2026

PROJECT MP12252

The following classification changes will be effected by this Notice of Changes:

Action	Subclass	Group(s)
SCHEME:		
Titles Changed:	H01C	1/14
	H01C	7/02,7/021,7/04,7/041,7/049,7/12,7/13
	H01C	13/02
	H01C	17/02, 17/06506, 17/075, 17/242
DEFINITIONS:		
Definitions New:	H01C	1/022
	H01C	7/02, 7/06, 7/18
	H01C	10/16
	H01C	17/006, 17/02, 17/06506, 17/28
Definitions Modified:	H01C	Subclass
	H01C	1/012, 1/14, 1/148
	H01C	7/00, 7/102, 7/105, 7/12

No other subclasses/groups are impacted by this Notice of Changes.

This Notice of Changes includes the following [Check the ones included]:

1. CLASSIF	TCATION SCHEME CHANGES
\boxtimes	A. New, Modified or Deleted Group(s)
	B. New, Modified or Deleted Warning(s)
	C. New, Modified or Deleted Note(s)
	D. New, Modified or Deleted Guidance Heading(s)
2. DEFINIT	TONS
\boxtimes	A. New or Modified Definitions (Full definition template)
	B. Modified or Deleted Definitions (Definitions Quick Fix)
3. 🗆 REVI	SION CONCORDANCE LIST (RCL)
4. 🗆 CHA	NGES TO THE CPC-TO-IPC CONCORDANCE LIST (CICL)
5. 🗆 CHA	NGES TO THE CROSS-REFERENCE LIST (CRL)

DATE: JANUARY 1, 2026

PROJECT MP12252

1. CLASSIFICATION SCHEME CHANGES

A. New, Modified or Deleted Group(s)

SUBCLASS H01C - RESISTORS

Type*	<u>Symbol</u>	Indent Level Number of	Title "CPC only" text should normally be enclosed	Transferred to#
		dots (e.g. 0,	in {curly brackets}**	
		$\frac{1,2)}{1}$	<u></u>	
		<u> </u>		
M	H01C1/14	1	Terminals or tapping points specially adapted	
			for resistors; Arrangements of terminals or	
			tapping points on resistors	
M	H01C7/02	1	having positive temperature coefficient	
M	H01C7/021	2	{formed with two or more layers}	
M	H01C7/04	1	having negative temperature coefficient	
M	H01C7/041	2	{formed with two or more layers}	
M	H01C7/049	2	{mainly consisting of organic or organo-metal	
			substances}	
M	H01C7/12	2	Overvoltage protection resistors; Arresters	
M	H01C7/13	1	current-responsive	
M	H01C13/02	1	Structural combinations of resistors	
M	H01C17/02	1	adapted for manufacturing resistors with	
			envelope or housing (apparatus or processes for	
			filling or compressing insulating material in	
			heating element tubes H05B3/52)	
M	H01C17/06506	3	{Precursor compositions therefor, e.g. pastes,	
			inks, glass frits or green body}	
M	H01C17/075	2	by thin-film techniques	
M	H01C17/242	3	by laser	

^{*}N = new entries where reclassification into entries is involved; C = entries with modified file scope where reclassification of documents from the entries is involved; Q = new entries which are firstly populated with documents via administrative transfers from deleted (D) entries. Afterwards, the transferred documents into the Q entry will either stay or be moved to more appropriate entries, as determined by intellectual reclassification; T = existing entries with enlarged file scope, which receive documents from C or D entries, e.g. when a limiting reference is removed from the entry title; M = entries with no change to the file scope (no reclassification); D = deleted entries; F = frozen entries will be deleted once reclassification of documents from the entries is completed; U = entries that are unchanged.

NOTES:

- **No {curly brackets} are used for titles in CPC only <u>subclasses</u>, e.g. C12Y, A23Y; 2000 series symbol titles of groups found at the end of schemes (orthogonal codes); or the Y section titles. The {curly brackets} <u>are</u> used for 2000 series symbol titles found interspersed throughout the main trunk schemes (breakdown codes).
- U groups: it is obligatory to display the required "anchor" symbol (U group), i.e. the entry immediately preceding a new group or an array of new groups to be created (in case new groups are not clearly subgroups of C-type groups). Always include the symbol, indent level and title of the U group in the table above.
- All entry types should be included in the scheme changes table above for better understanding of the overall scheme change picture. Symbol, indent level, and title are required for all types.
- "Transferred to" column <u>must</u> be completed for all C, D, F, and Q type entries. F groups will be deleted once reclassification is completed.
- When multiple symbols are included in the "Transferred to" column, avoid using ranges of symbols in order to be as precise as possible.

DATE: JANUARY 1, 2026

PROJECT MP12252

- For administrative transfer of documents, the following text should be used: "<administrative transfer to XX>", "<administrative transfer to XX and YY simultaneously>", or "<administrative transfer to XX, YY, ...and ZZ simultaneously>" when administrative transfer of the same documents is to more than one place.
- Administrative transfer to main trunk groups is assumed to be the source allocation type, unless otherwise indicated.
- Administrative transfer to 2000/Y series groups is assumed to be "additional information".
- If needed, instructions for allocation type should be indicated within the angle brackets using the abbreviations "ADD" or "INV": <administrative transfer to XX ADD>, <administrative transfer to XX INV>, or <administrative transfer to XX ADD, YY INV, ... and ZZ ADD simultaneously>.
- In certain situations, the "D" entries of 2000-series or Y-series groups may not require a destination ("Transferred to") symbol, however it is required to specify "<no transfer>" in the "Transferred to" column for such cases.
- For finalisation projects, the deleted "F" symbols should have <no transfer> in the "Transferred to" column.
- For more details about the types of scheme change, see CPC Guide.

DATE: JANUARY 1, 2026

PROJECT MP12252

2. A. DEFINITIONS (new)

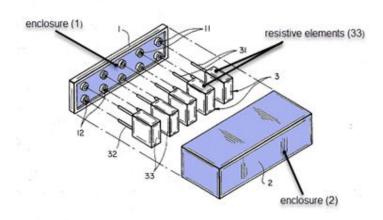
H01C1/022

Definition statement

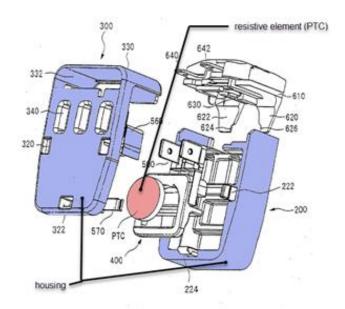
This place covers:

Illustrative examples of subject matter classified in this place:

1. Structural arrangement of resistive elements



2. PTC thermistor arrangement



DATE: JANUARY 1, 2026

PROJECT MP12252

H01C7/02

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

I Ceramics	L COAF	2
	I CU4L	_

H01C7/06

Definition statement

This place covers:

Chemical compositions, materials or arrangements with terminals, to minimize changes in resistance with changes in temperature.

H01C7/18

Definition statement

This place covers:

Resistors formed by two or more layers stacked between terminals.

- The plurality of layers can include ceramic and conductive layers.
- The plurality of layers can include stacking of resistor components.

DATE: JANUARY 1, 2026

PROJECT MP12252

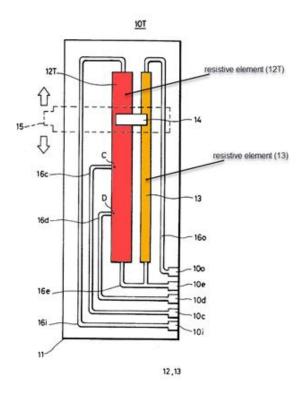
H01C10/16

Definition statement

This place covers:

Illustrative example of subject matter classified in this place:

Adjustable resistor



H01C17/006

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

	Resistors as a component of an integrated circuit	H10D1/47
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DATE: JANUARY 1, 2026

PROJECT MP12252

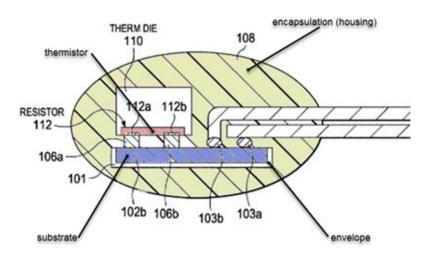
H01C17/02

Definition statement

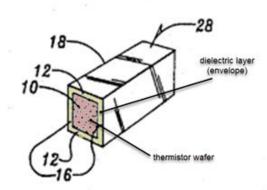
This place covers:

Illustrative examples of subject matter classified in this place:

1. Encapsulated resistor



2. Encapsulated resistor



DATE: JANUARY 1, 2026

PROJECT MP12252

H01C17/06506

Definition statement

This place covers:

- Precursor compositions per se that may or may not be adapted for coating on a base.
- The base can be a support or supporting member, e.g. substrate.

H01C17/28

Definition statement

This place covers:

- Terminals or electrodes.
- The terminals can be applied to single layer resistive elements or multilayer resistive elements.

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

Terminal	s coated on resistive element	H01C1/142
	, coated on recipies cierron	1101011

DATE: JANUARY 1, 2026

PROJECT MP12252

2. A. DEFINITIONS (modified)

H₀1C

Definition statement

Replace:

The word "pirolytic" in the eighth bullet point of the existing Definition statement with the updated word "pyrolytic", so that the updated bullet point appears as follows.

 Apparatus or processes specially adapted for manufacturing resistors adapted for manufacturing resistor chips, for manufacturing resistors with envelope or housing, for winding the resistive element or for coating resistive material on a base, e.g. by thick (including precursor compositions therefor) or thin film techniques (e.g. vapour or chemical deposition, sputtering or flame spraying) by pyrolytic processes or by resistor foil bonding; adapted for trimming, for applying terminals or for baking.

References

Limiting references

Replace: The existing Limiting references table with the following updated table.

Apparatus or processes for filling or compressing insulating material in heating element tubes	H05B3/52
Resistors having potential barriers, e.g. field-effect resistors	H10D1/40 - H10D1/43
Photoresistors and similar semiconductors devices in which radiation controls flow of current through the device	H10F30/00
Organic resistors having potential barriers	H10K10/10
Magnetic-field-controlled resistors and similar devices using galvano-magnetic or similar magnetic effects	H10N50/00
Hall-effect devices	H10N52/00
Bulk negative resistance effect devices	H10N80/00

DATE: JANUARY 1, 2026

PROJECT MP12252

Informative references

Replace: The existing Informative references table with the following updated table.

Powder metallurgy	B22F
Trimming of electrical components	B23K26/351
Layered products	B32B
Compositions of ceramic materials, e.g. for resistors or varistors and	C04B35/453
based on zinc oxides	
Compositions of ceramic materials, e.g. for resistors or thermistors,	C04B35/46
and based on titanium oxide or titanates	
Compositions of ceramic materials, e.g. for resistors or thermistors,	C04B35/48
and based on zirconium oxides or zirconates	
Compositions of ceramic materials, e.g. for resistors or thermistors,	C04B35/495
and based on vanadium, niobium, tantalum, molybdenum or	
tungsten oxides or vanadates, niobates, tantalates, molybdates or	
tungstates	
Polymeric films or sheets	C08J5/18
Indicating or measuring liquid level, or level of fluent solid material by	G01F23/24
measuring variations of resistance of resistors due to contact with	
conductor fluid	0.041107/04
Investigating or analysing material by investigating resistance	G01N27/04
Arrangements for measuring resistance	G01R27/00
Measuring dielectric properties, e.g. dielectric constants	G01R27/2617
Selection of specified materials as dielectric	H01B3/00
Terminals or tapping points in general	H01R
Overvoltage arresters using spark gaps	H01T4/00
Emergency protective circuit arrangements responsive to excess	H02H9/02
current	1100110/04
Emergency protective circuit arrangements responsive to excess	H02H9/04
Voltage	H05B3/00
Ohmic-resistance heating	H05K1/16
Printed circuits incorporating printed electric components, e.g.	HUOK I/ IO
printed resistor, capacitor or inductor	H05K1/18
Printed circuits structurally associated with non-printed electric	HUOK I/ TO
Components Conjugation of the control of the contro	HOEKE/OO
Casings for electrical apparatus in general Passive two-terminal components without a potential-jump or surface	H05K5/00
barrier for integrated circuits	וו עטווון וויי
Devices using superconductivity or hyperconductivity	H10N60/00
Solid state devices for rectifying, amplifying, oscillating or switching	H10N70/00
having no potential barrier	11101170/00
Thin- or thick-film solid state devices	H10N97/00
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DATE: JANUARY 1, 2026

PROJECT MP12252

Replace: The second paragraph of the existing Special rules text with the following

updated text. The first paragraph is unchanged.

Special rules of classification

Electrodes and terminals for resistors in main group H01C7/00 are covered by main group H01C1/00, more specifically group H01C1/14 and subgroups.

Glossary of terms

Replace: The text in the second row of the existing Glossary of terms table with the

following updated text, so that the updated text appears as follows. The

other two rows are unchanged.

varistor	also referred as voltage dependent resistor
	is a resistor that conducts significantly
	increased current when voltage is
	excessive

Delete: The entire Synonyms and Keywords section.

H01C1/012

<u>Insert</u>: The following new Definition statement.

Definition statement

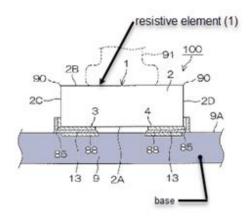
This place covers:

Illustrative examples of subject matter classified in this place:

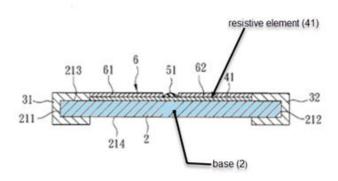
1. Resistive element mounted on a printed circuit support

DATE: JANUARY 1, 2026

PROJECT MP12252



2. Terminals embracing the resistive elements



References

Limiting references

Replace: The existing Limiting references table with the following updated table.

Compensation for resistor expansion or contraction	H01C1/016
Resistive elements being formed in two or more coils or loops as a spiral, helical or toroidal winding wound on a flat or ribbon base	H01C3/18
Resistive elements being formed in two or more coils or loops as a spiral, helical or toroidal winding wound on cylindrical or prismatic base	H01C3/20
Resistive elements being formed as one or more layers or coatings on a base	H01C7/00

DATE: JANUARY 1, 2026

PROJECT MP12252

<u>Insert</u>: The following new Glossary of terms section.

Glossary of terms

In this place, the following terms or expressions are used with the meaning indicated:

base	substrate or support member
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H01C1/14

<u>Insert</u>: The following new Synonyms and Keywords section.

Synonyms and Keywords

In patent documents, the following words/expressions are often used as synonyms:

• "terminals", "electrodes", "leads", "conductors"

H01C1/148

<u>Insert</u>: The following new Definition statement.

Definition statement

This place covers:

Resistive element having multilayers.

DATE: JANUARY 1, 2026

PROJECT MP12252

H01C7/00

References

Limiting references

Insert: The following one new row into the existing Limiting references table.

Organic resistors having potential barriers	H10K10/10
---	-----------

H01C7/102

<u>Insert</u>: The following new Definition statement.

Definition statement

This place covers:

The structure of the varistor boundary, e.g. surface layers.

H01C7/105

<u>Insert</u>: The following new Definition statement.

Definition statement

This place covers:

The structure of varistor cores.

DATE: JANUARY 1, 2026

PROJECT MP12252

H01C7/12

<u>Insert</u>: The following new Definition statement.

Definition statement

This place covers:

Resistors that provide protection of electronic components from voltage surges.